

1. Features

- $R_{DS(on)}=2.1\text{m}\Omega$ (typ.) @ $V_{GS}=10\text{V}$
- Low On-Resistance
- 5V Logic Level Control
- 100% Avalanche Tested
- Lead-Free, RoHS Compliant

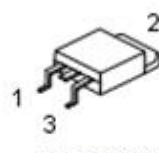
2. Features

KNX2803B designed by the trench processing techniques to achieve extremely low on-resistance. Additional features of this design are a 150°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in Motor applications and a wide variety of other applications.

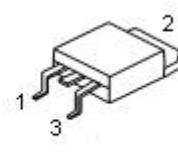
3. Pin configuration



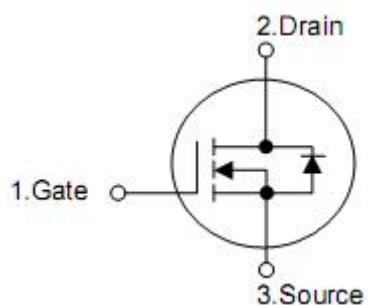
DFN5*6



TO-252



TO-263



Pin DFN5*6	Pin TO-263	Function
4	1	Gate
5,6,7,8	2	Drain
1,2,3	3	Source

4. Ordering Information

Part Number	Package	Brand
KND2803B	TO-252	KIA
KNB2803B	TO-263	KIA
KNX2803B	DFN5*6	KIA

5. Absolute maximum ratings

Parameter	Symbol	Ratings		Units
		TO-252 DNF5*6	TO-263	
Drain-source voltage	V_{DSS}	30		V
Gate-source voltage	V_{GSS}	± 20		V
Continuous Drain Current($VGS=4.5V$) ³	I_D	150		A
		105		
Pulsed drain current tested $T_c=25\text{ }^\circ\text{C}$ ¹	I_{DM}	600		A
Avalanche energy single pulse ²	E_{AS}	625		mJ
Maximum Power dissipation $T_c=25\text{ }^\circ\text{C}$	P_D	50	160	W
Maximum junction temperature	T_J	150		$^\circ\text{C}$
Storage temperature range	T_{STG}	-55~+150		$^\circ\text{C}$

6. Thermal characteristics

Parameter	Symbol	Rating		Unit
		TO-252 DFN5*6	TO-263	
Thermal resistance,Junction-to-case	R_{thJC}	2.5	0.79	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-Ambient ²	R_{thJA}	62		$^\circ\text{C}/\text{W}$

7. Electrical characteristics

($T_c=25^\circ\text{C}$,unless otherwise notes)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
Drain-to-source leakage current	$I_{\text{DS}(\text{off})}$	$V_{\text{DS}}=24\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$T_c=125^\circ\text{C}$	-	-	100	μA
Gate-to-source leakage current	I_{GSS}	$V_{\text{GS}}=20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	100	nA
		$V_{\text{GS}}=-20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	-100	nA
On characteristics						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.6	3.0	V
Static drain-source on-resistance ¹	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$	-	2.1	2.8	$\text{m}\Omega$
Static drain-source on-resistance ¹	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=40\text{A}$	-	2.6	3.8	$\text{m}\Omega$
Dynamic characteristics						
Input capacitance	C_{iss}	$V_{\text{DS}}=24\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	-	5060	-	pF
Output capacitance	C_{oss}		-	500	-	
Reverse transfer capacitance	C_{rss}		-	206	-	
Total gate charge	Q_g	$V_{\text{DS}}=24\text{V}, I_{\text{D}}=15\text{A}, V_{\text{GS}}=10\text{V}$	-	90	-	nC
Gate-source charge	Q_{gs}		-	28	-	
Gate-drain (Miller)charge	Q_{gd}		-	60	-	
Resistive switching characteristics						
Turn-on delay time	$T_{\text{d}(\text{ON})}$	$V_{\text{DD}}=18\text{V}, I_{\text{D}}=80\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=3.3\Omega$	-	33	-	nS
Rise time	t_{rise}		-	60	-	
Turn-off delay time	$T_{\text{d}(\text{OFF})}$		-	36	-	
Fall time	t_{fall}		-	42	-	
Source-drain body diode characteristics						
Diode continuous forward current ¹	I_{SD}	$T_j=25^\circ\text{C}$	-	-	150	A
Diode forward voltage ¹	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{SD}}=20\text{A}$	-	0.82	1.3	V

Note: 1. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

2. Limited by T_{jmax} , Starting $T_j=25^\circ\text{C}, L=1\text{mH}, R_{\text{G}}=25\Omega, I_{\text{AS}}=36\text{A}, V_{\text{GS}}=10\text{V}$,

Part not recommended for use above this value.

3. Repetitive rating; pulse width limited by max. junction temperature.

8.Typical characteristics

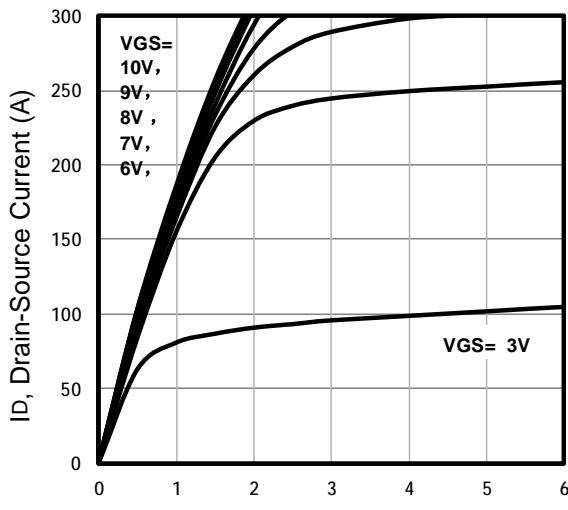


Fig1. Typical Output Characteristics

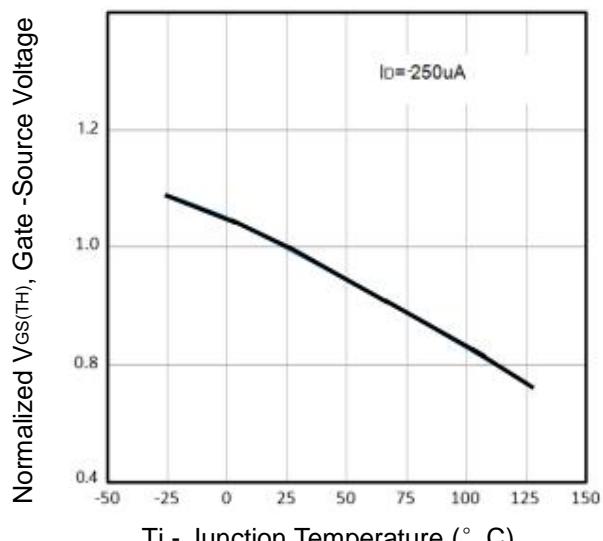


Fig2. Normalized Threshold Voltage Vs. Temperature

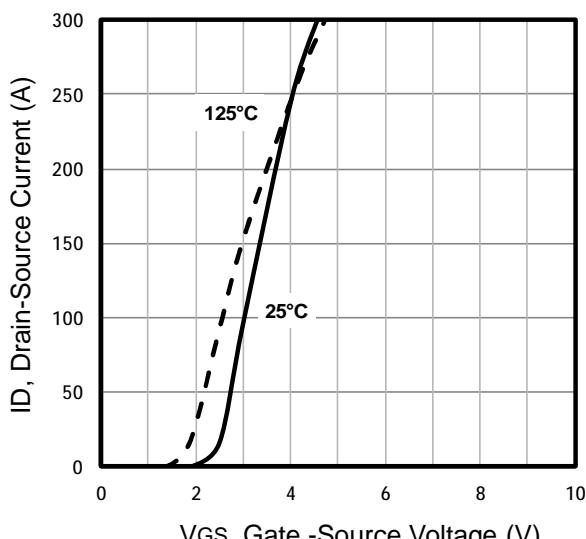


Fig3. Typical Transfer Characteristics

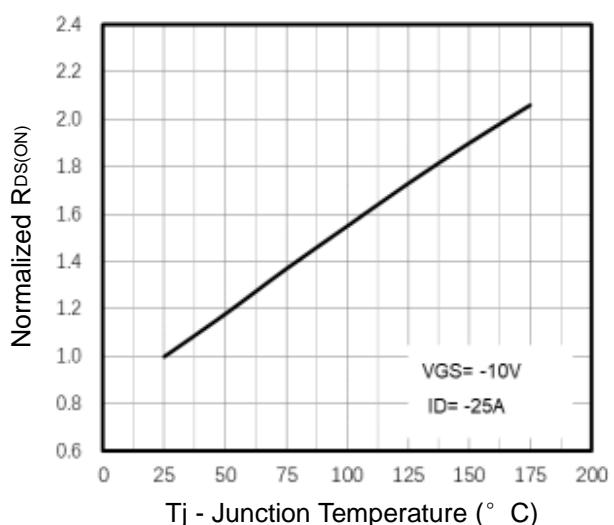


Fig4. Normalized Threshold Voltage Vs. Temperature

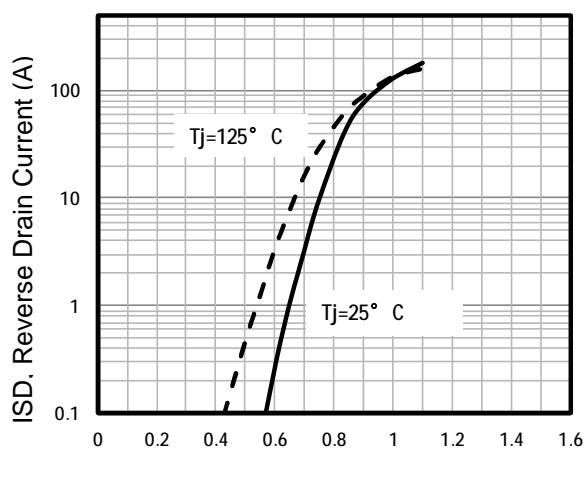


Fig5. Typical Source-Drain Diode Forward

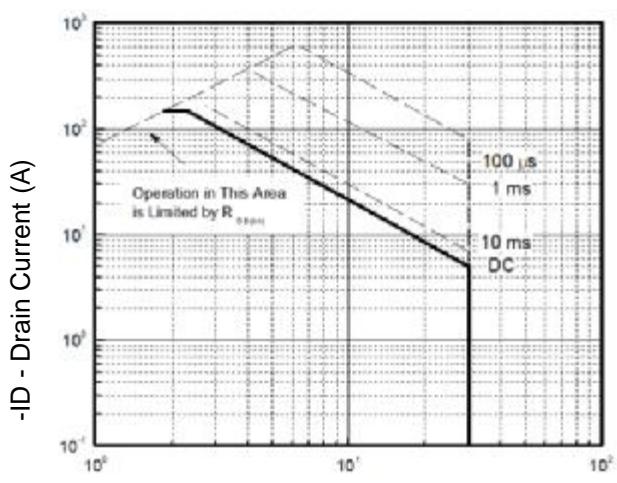


Fig6. Maximum Safe Operating Area

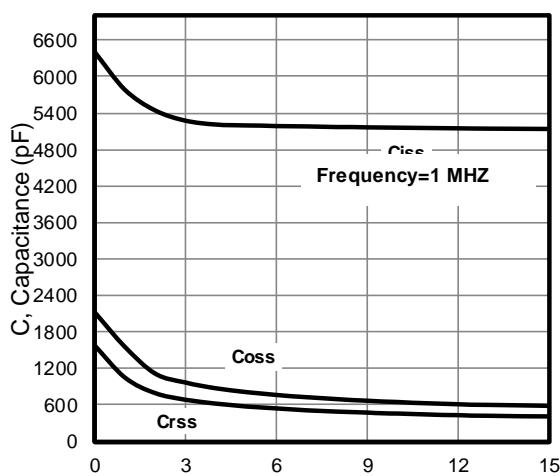


Fig7. Typical Capacitance Vs. Drain-Source Voltage

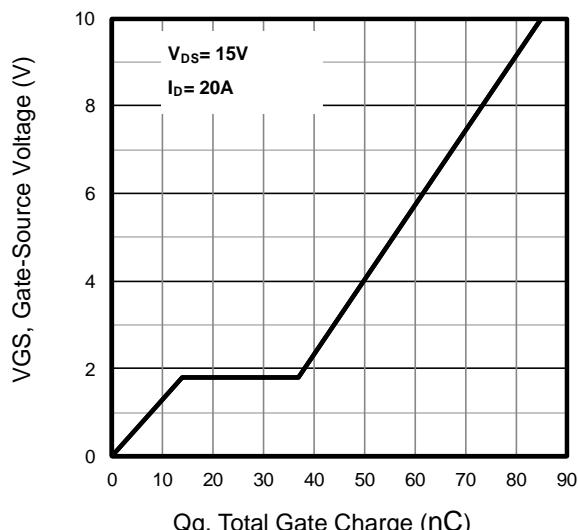


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

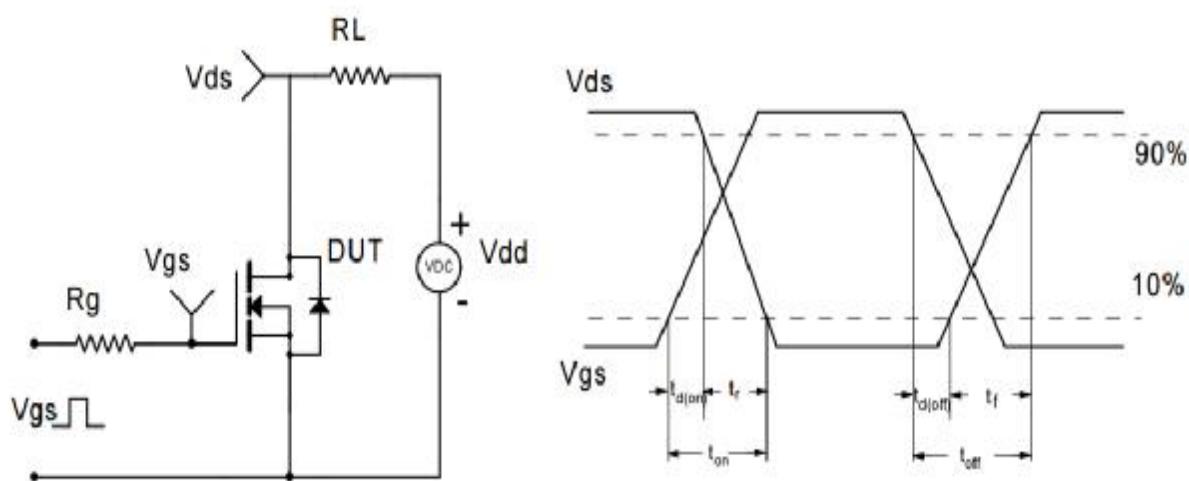


Fig9. Switching Time Test Circuit and waveforms